

MWT Silicon Heterojunction

A Simple Technology Integrating High Performance Cell and
Module Technologies

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Hercules workshop, Berlin

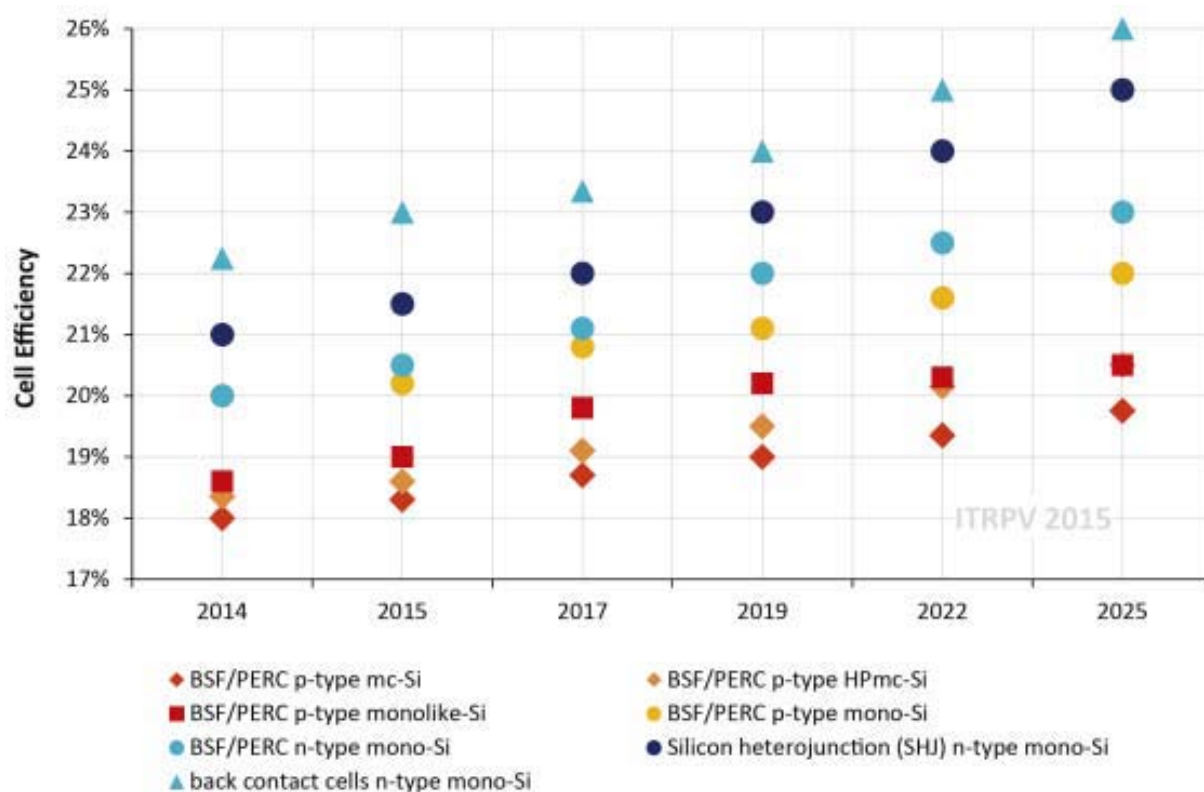
11 October 2016

Content

- PV evolution according to ITRPV
- From Cell to Module
- ECN developments foil based back-contact cells and module technologies
 - Thin cells
 - Cost reduction of module materials
 - Outdoor test data
 - *MWT-HJ cells and implications for modules*
 - View towards applications
- Summary and Outlook

From standard to High η Si cell concepts

- From p- to n-type front to back contacted (PERT, HJ)
- From front to back contact to back contact (MWT,IBC)
- From monofacial to bifacial (> kWh/kWp)



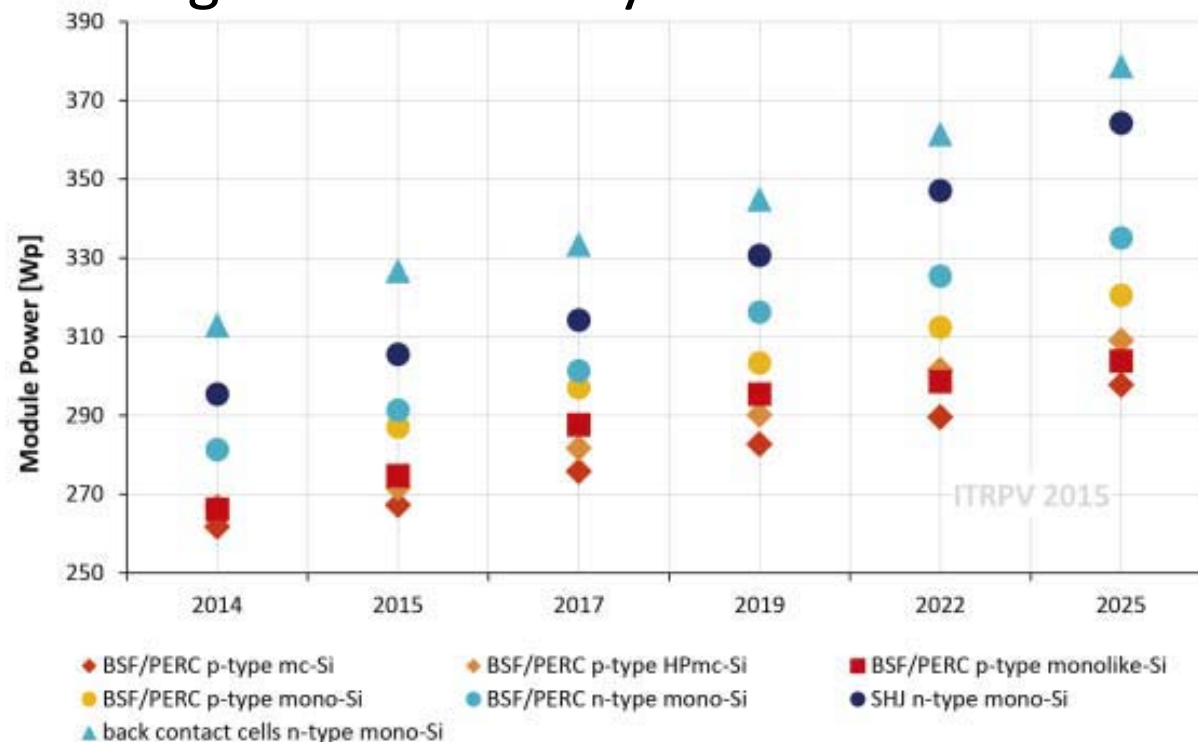
N mono IBC
N mono HJ

N mono PERC
P mono PERC
P monolike PERC
P multi PERC

ITRPV roadmap 2015

To be translated to High Power modules

- Products: 60 cells 156 mm
- Optimize CtM
- Low cost without sacrificing quality and reliability
- Long term reliability is crucial for stable growth



ITRPV roadmap 2015

Expected market shares

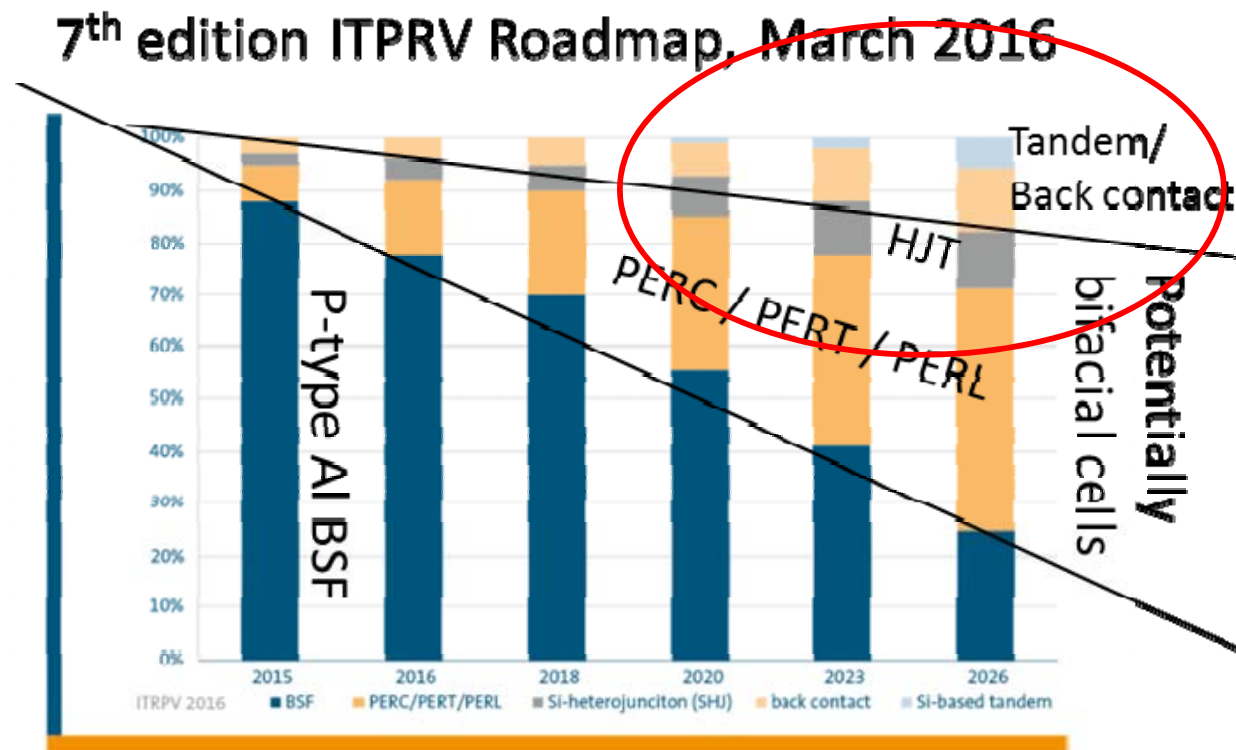


Fig. 33: Worldwide market shares for different cell technologies.

Trends according to ITRPV roadmap:

- PERC concepts will become mainstream
- **Back Contact and HJ concepts expected to increase for niche markets**

How to adapt the module technology so that it fits with a specific cell concept

Each cell concept has to be individually evaluated for the best module concept in terms of:

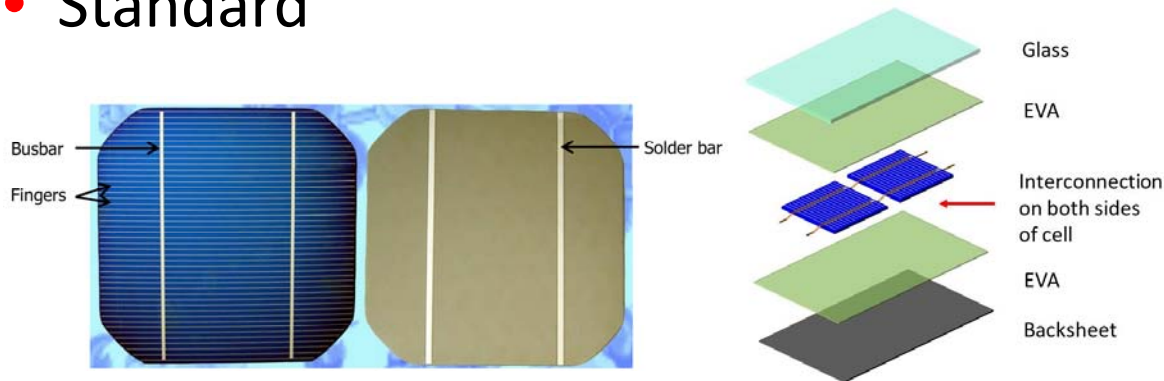
- Long term stability → >30 years product lifetime
- Lowest cell to module losses → CtM value
- Optimized production costs → high yields, low investment costs
- Optimized Bill of Materials (BoM)
- Best energy yield → temperature, low light, incident angle, shadow...

There are special requirements for individual concepts, a.o.

- IBC: soldering not trivial
- SHJ: low Temperature interconnection, barrier for moisture ingress
- Etc...

From cell to module.... different approaches

- Standard

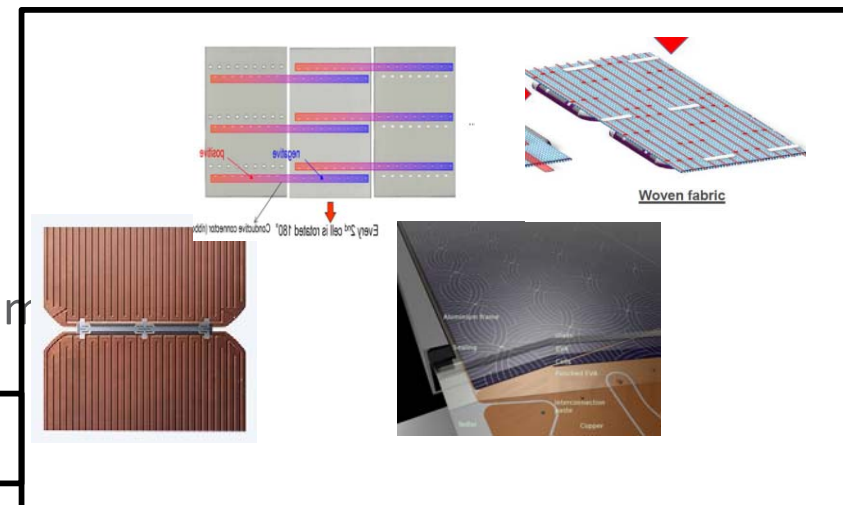
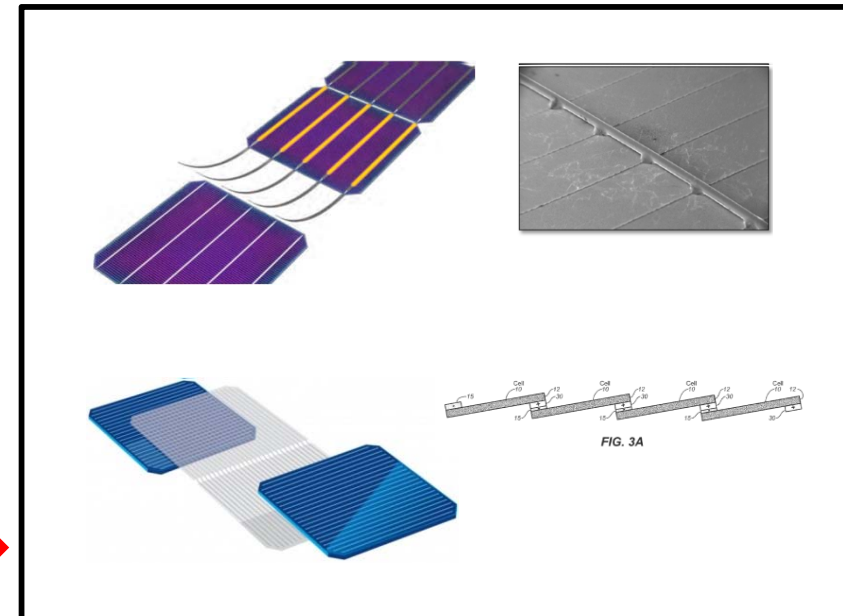


- Front to rear contact (Perc, HJ) →

- Move to more busbars: 2,3,4,5
- No Busbars: Multiwire/smartwire (Schmid, MB)
- Shingling, cascading (Sunpower, Silevo)

- Back Contact (MWT, IBC) →

- Rear soldering (tabbing, woven fabrics, MW) (ISE, ir)
- Smart tab edge interconnection (Sunpower)
- **Foil interconnection technology (ECN, Eurotron,..)**

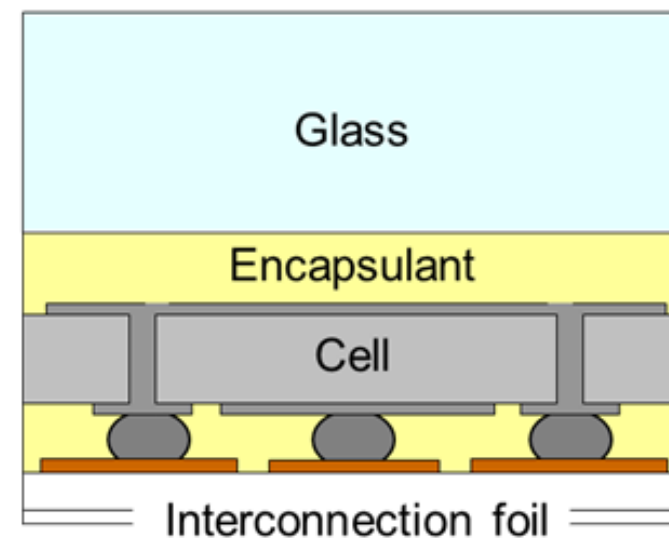
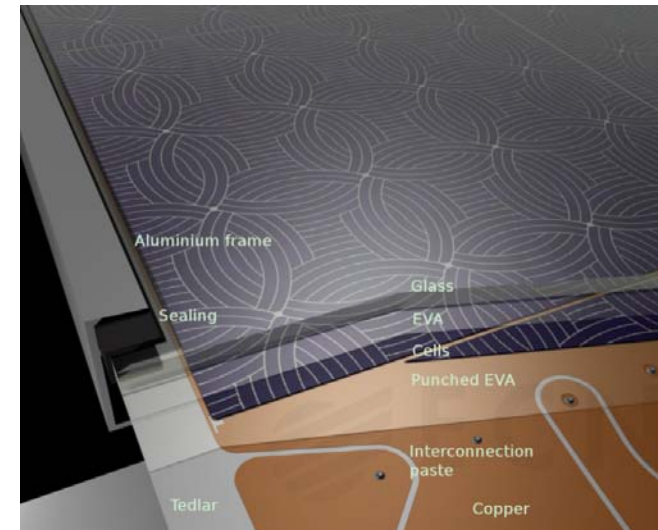


Cell to module: Back Contact



MWT, IBC: foil

- Conductive back-sheet foil
 - Copper as conductive layer
 - Patterning by chemical etching or milling
- Contact cell to foil through conductive adhesive
 - Printed on foil
- Isolation cell from foil by encapsulant
 - Holes at contacts



Cell to module: Back Contact



- Reliability proven
 - IEC certification achieved
- Production equipment developed by Eurotron: high level of automisation
 - >300 Wp nMWT certified
 - >280 Wp IBC (120 micron cells, special BoM design for recycling)



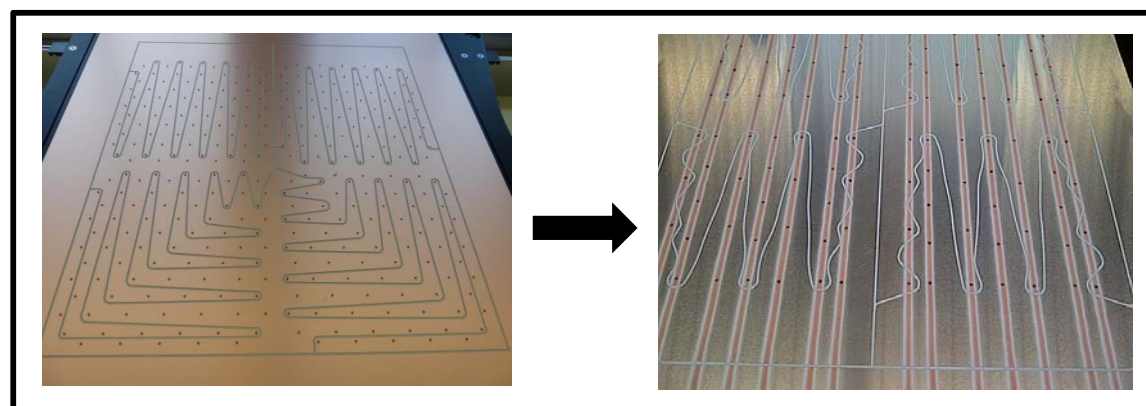
Back Contact Module R&D at ECN

- BoM testing in mini pilot module line: 4 cells modules as scale model for large area module
 - Integration of (thin) BC cells from ECN cell baselines or other sources
 - Comparison of module materials and new processes
 - CtM power optimization by optical and electrical engineering
 - Reliability , outdoor testing
 - Special prototypes



6 via MWT

All black IBC



Cu CBS

Cu Coldspray on Al CBS

Cell-to-module change

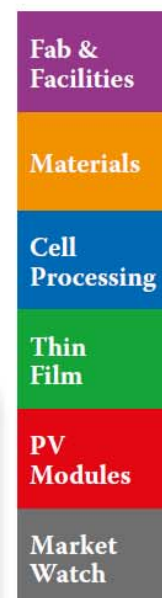
- A paper is published in PV-International this month on CtM changes specifically for back-contact module technology

Positive cell-to-module change: Getting more power out of back-contact modules

Bas B. van Aken & Lenneke H. Slooff-Hoek, ECN – Solar Energy, Petten, The Netherlands

ABSTRACT

Cell-to-module (CtM) loss is the loss in power when a number of cells are interconnected and laminated in the creation of a PV module. These losses can be differentiated into *optical losses*, leading to a lower photogenerated current, and *resistive losses*, leading to a decrease in fill factor. However, since the application of anti-reflection (AR) coatings and other optical 'tricks' can sometimes increase the I_{sc} of the module with respect to the average cell I_{sc} , the CtM loss in such cases needs to be expressed as a negative value, which gives rise to confusion. It is proposed to use the CtM change, where a negative value corresponds to a loss in current or power, and a positive value to a gain. In this paper, the CtM changes for back-contact modules utilizing a conductive foil are described and compared with other mature module technologies. A detailed analysis of the CtM change for a full-size metal-wrap-through (MWT) module is presented.

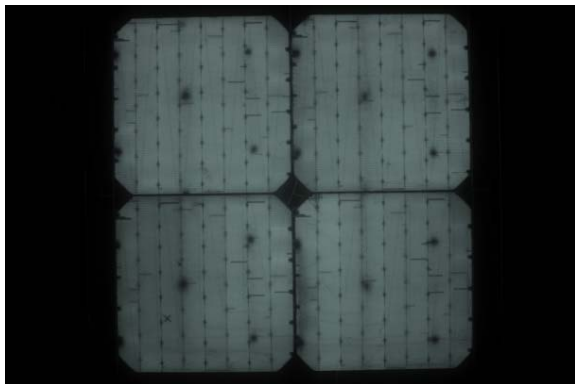


< € / m²

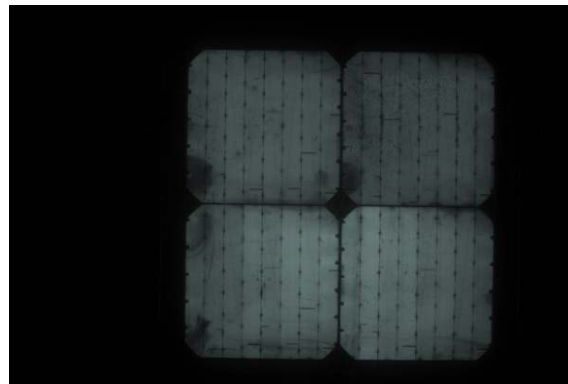


Handling of thin cells

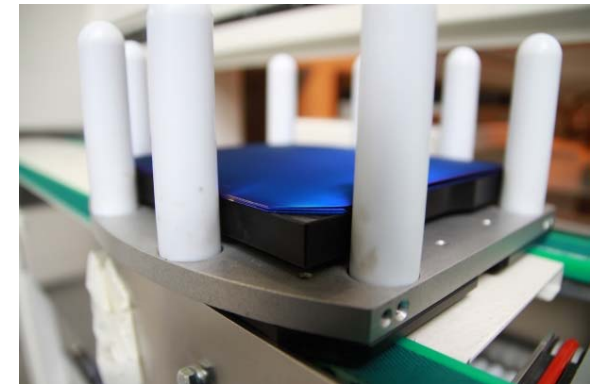
- IBC cells down to 80 micron cells with adapted processing
- 4 cells mini modules have been fabricated: no breakage/cracks and FF > 74 %
- Cell handling down to 80 micron proven with industrial module equipment (Eurotron)



100 micron



80 micron



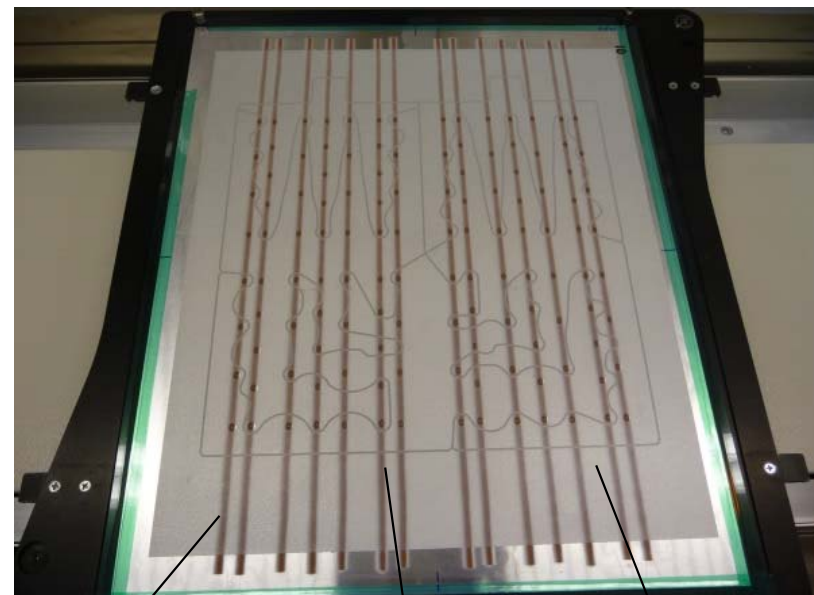
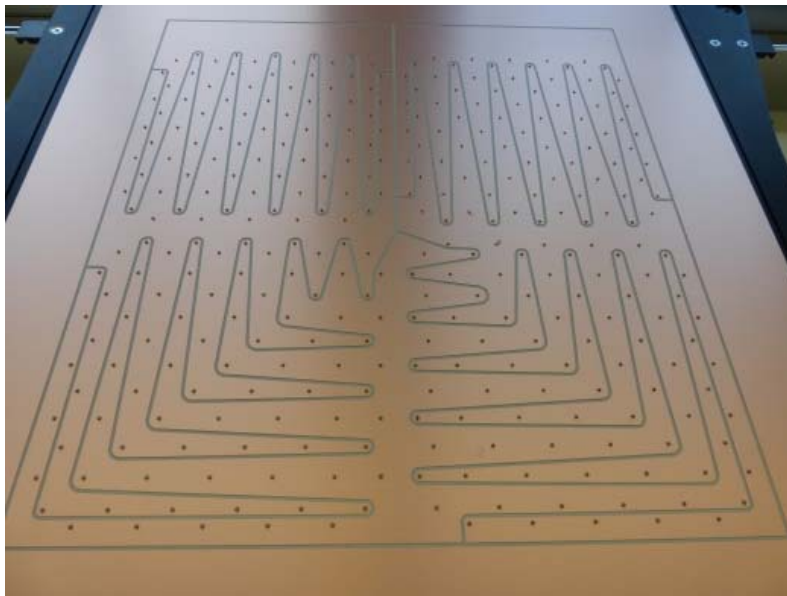
Automated handling
with industrial equipment

< € / m²



Reduction cost conductive back-sheet foil

- Replacing copper by aluminium
- Local application of Copper powder by Cold-Spray on Al foil
- Conductive adhesive printed on the Copper pads: < 1 mOhm R_c
- Potential cost saving ~3 Euro per full size backsheet



Goris et al. EUPVSEC 2016

Copper cold spray
(14 lines)

adhesive

Punched EVA

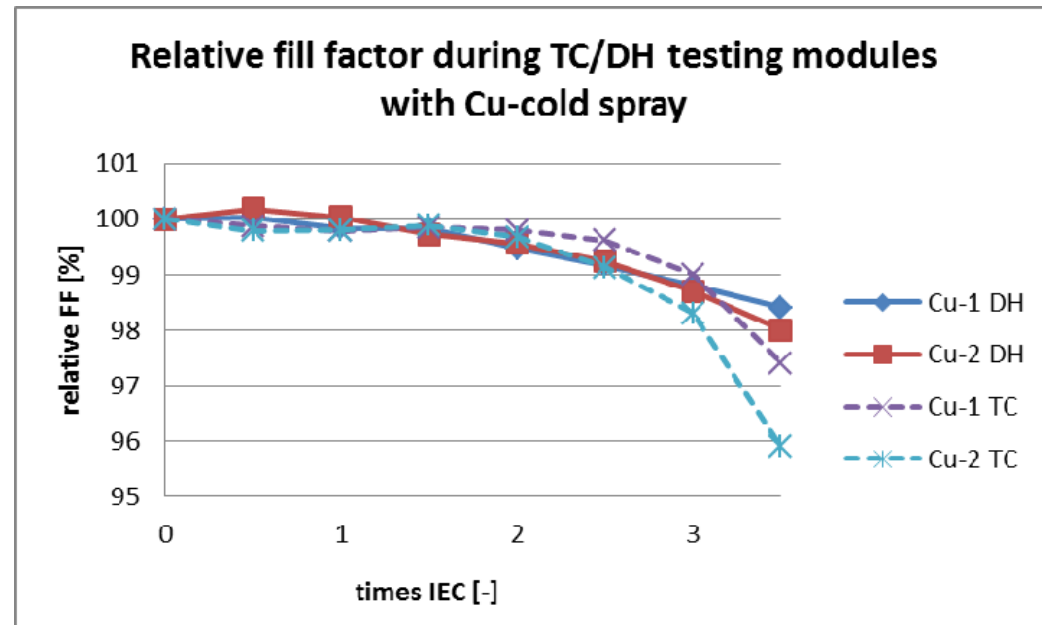
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Reduction cost conductive back-sheet foil

Performance MWT and IBC modules

Module	FF [%]
MWT on Cu	75.9
MWT on Al + CuCS	75.9
IBC on Cu	74.9
IBC on Al + CuCS	74.9



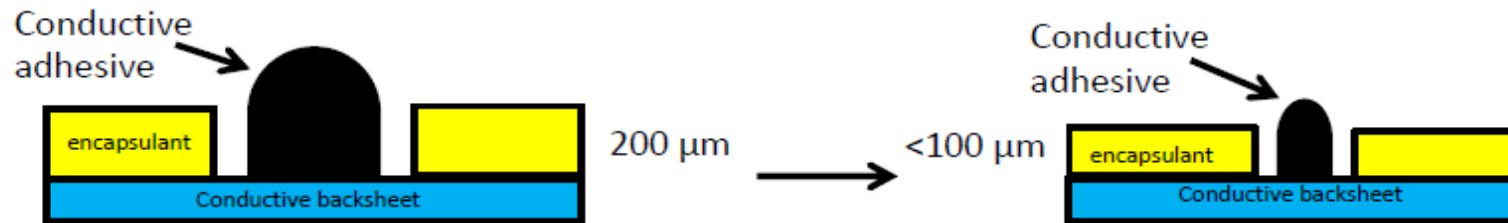
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MWT Modules passed 3.5 x IEC test!
Similar trends observed for IBC after 1 x IEC

< € / m²

Reduction cost conductive adhesive

- Reduction silver content from >80% to <20%
- Reduction volume by using thinner encapsulants → **Powder coating**
- More contact points possible without cost penalty



< € / m²

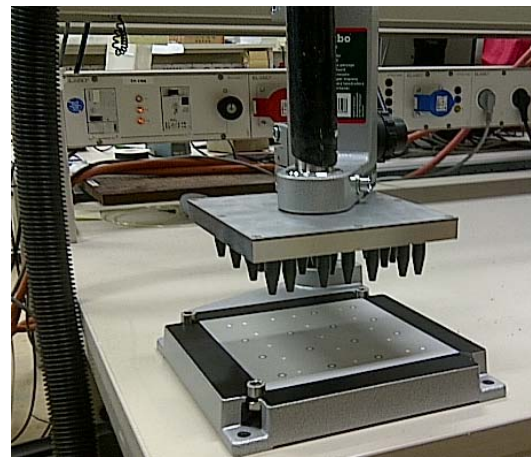
Reduction cost conductive adhesive

Powder coating process

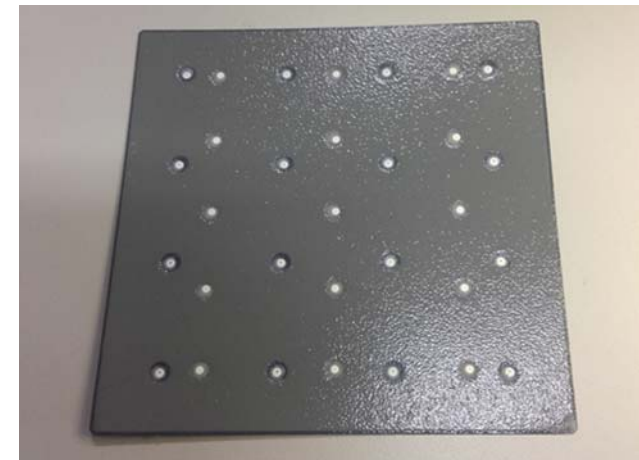
- Electrostatic deposition technique
- Large freedom to tune layer thickness
- Applied on solar cells and glass
- Cleaning contact pads (punching is eliminated)



Spray booth and controller



Contact point cleaner



Coated cell and clean contact points

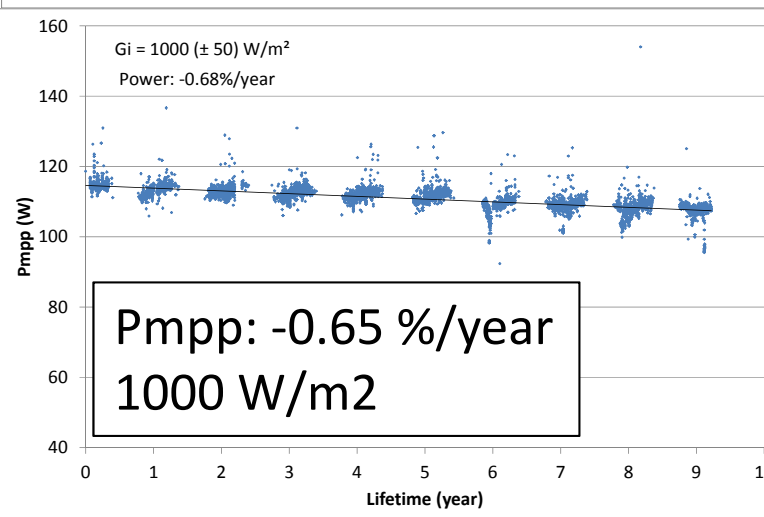
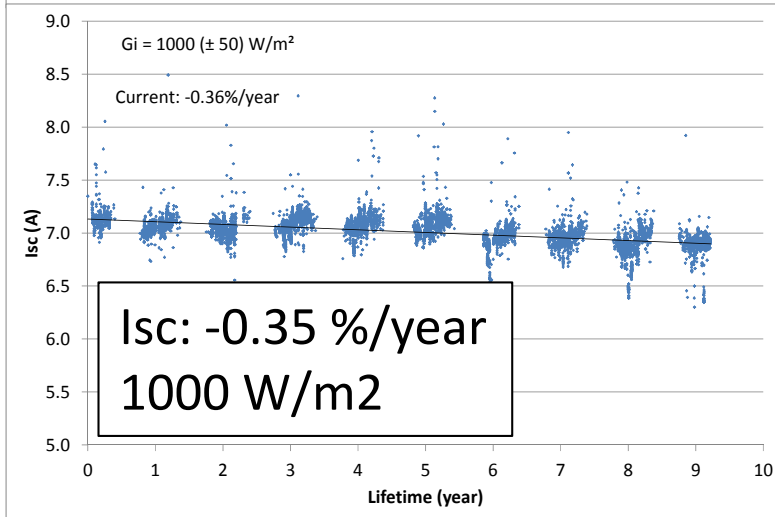
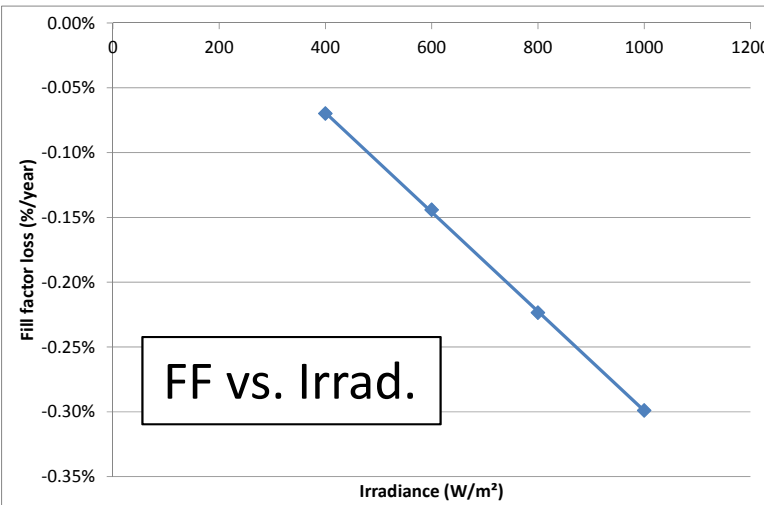
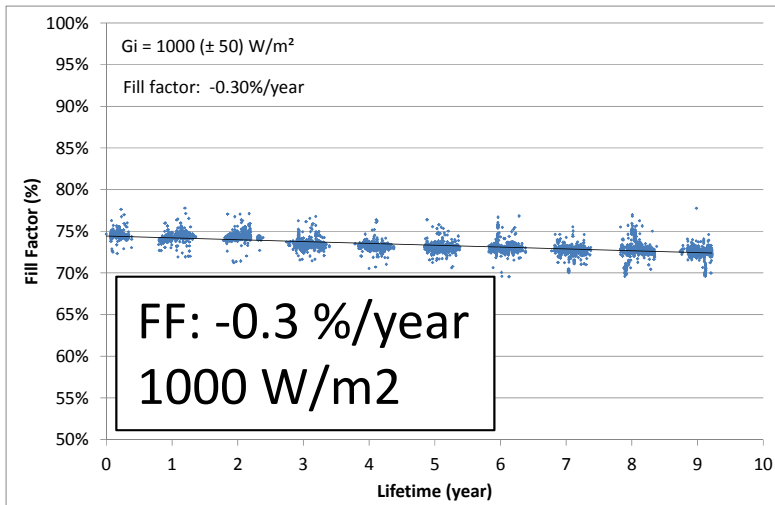
Reduction cost conductive adhesive

- MWT modules with Thermoplastic powder coated encapsulant on solar cell and glass: process proven for 150-200micron

Encapsulant	Isc (A)	Voc (V)	FF (%)	Pm(W)
Powder coat	8.81	2.52	75.9	16.82
EVA ref	8.75	2.52	75.9	16.66

- Challenge:
 - Find right materials that with stand IEC testing
 - Proof mechanical stability

Outdoor performance p-MWT module (2007-2016)



- FF loss
 - Electrical losses
- Isc loss:
 - No module cleaning

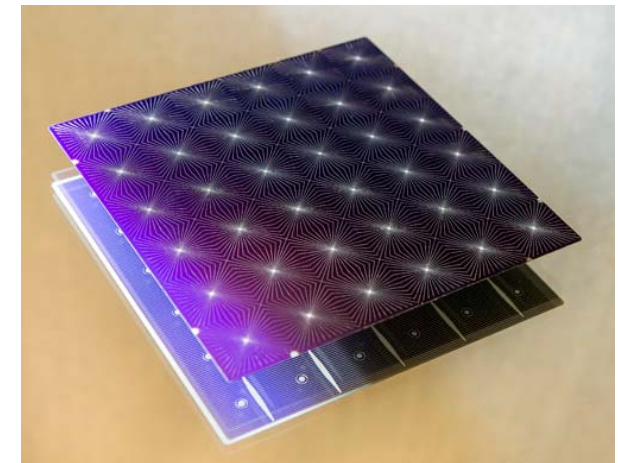
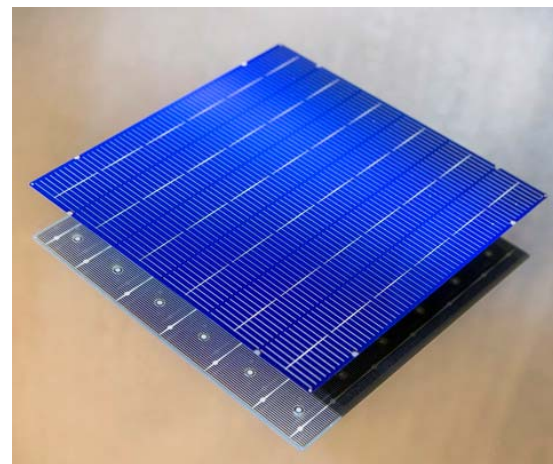
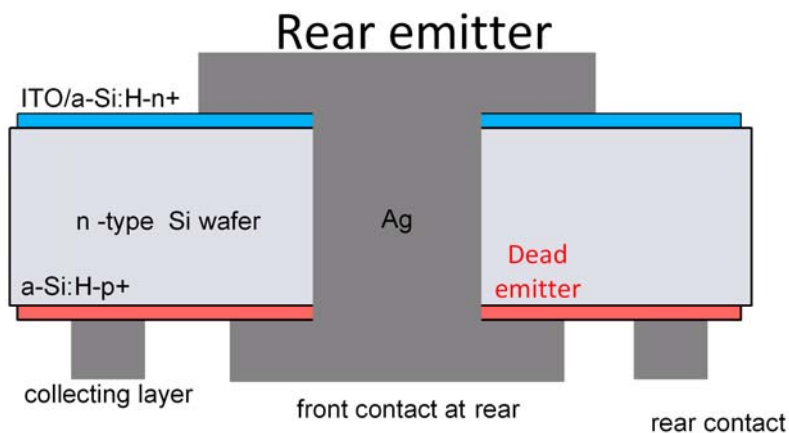


> W_p / m^2

Performance improvements? Back to cells.....



- MWT-SHJ combines advantages of silicon heterojunction (SHJ) and metal wrap through (MWT) technologies in one device:
 - SHJ shows record V_{oc} and has a low temperature coefficient for higher module energy yield
 - MWT shows Ag cost reduction and less shading in a module
 - Module technology meet low T requirements by soldering-free



> W_p / m^2



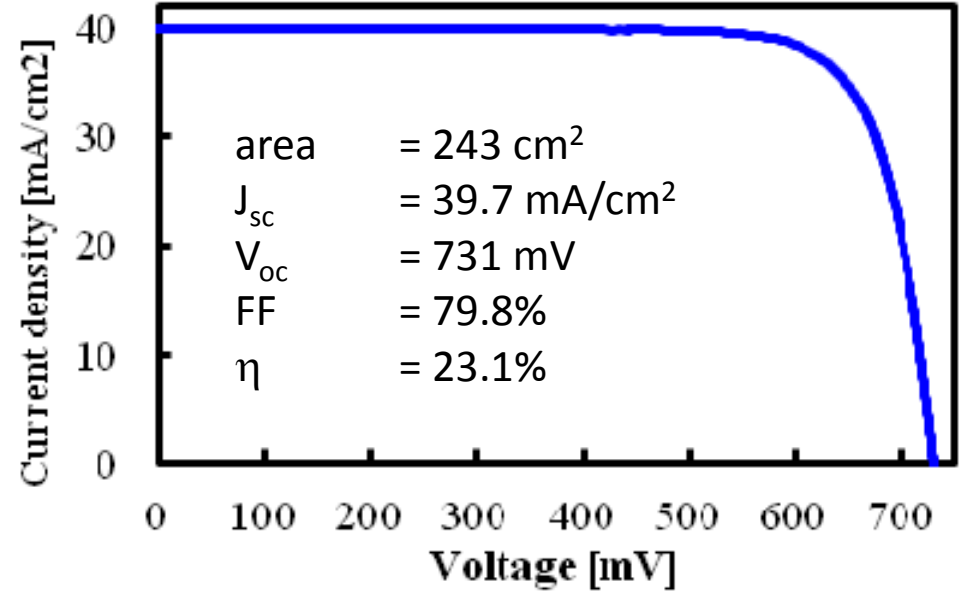
Results MWT-HJ cells

- Front side metallization improvements

From low T Ag to

Cu-plated, 6 x 6 vias
(developed at CIC)

Structure	Front metal	J_{sc} [mA/cm ²] (shading)	V_{oc} [mV]	FF [%]	η [%]
H-pattern	Ag 3BB*	38.9 (5.6%)	722	77.3	21.7
MWT 4x4	Ag	39.1 (3.7%)	726	76.6	21.7
MWT 6x6	Ag	39.2 (3.4%)	723	77.6	22.0
MWT 6x6	Ag	39.3	719	80.0	22.6



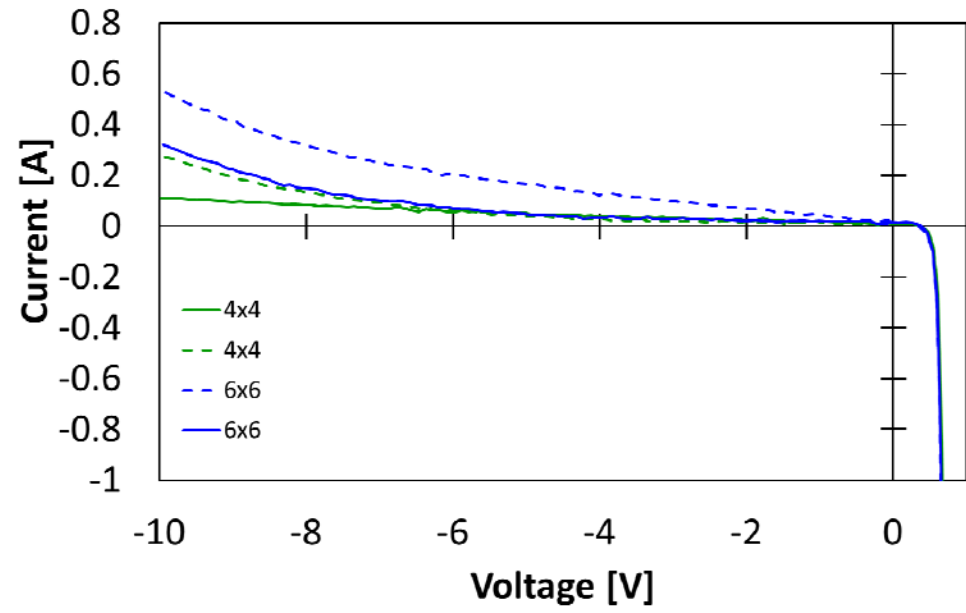
Coletti, EUPVSEC proc. 2016
Ishimura, EUPVSEC proc. 2016

> W_p / m^2



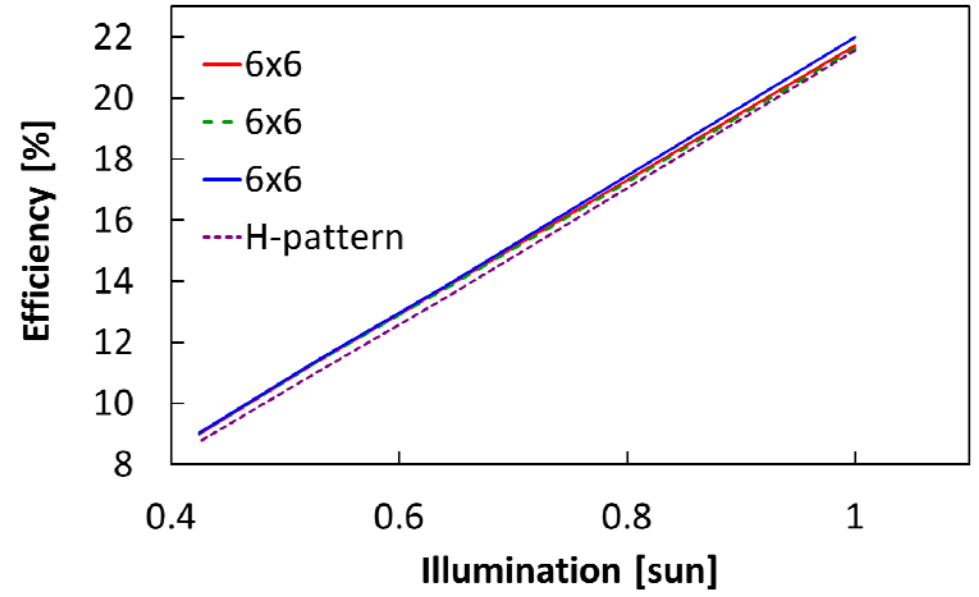
Results MWT-HJ cells

Reverse characteristics



$I_{rev} < 0.5 \text{ A}$ at -10 V for 4×4 and 6×6

Sensitivity towards illumination



Shunt and recombination behavior comparable to H pattern SHJ

From MWT HJ cell to module.....

Concept is ideally suited for conductive back sheet module technology as is IBC HJ

- Low Temperature interconnection
- Solder free

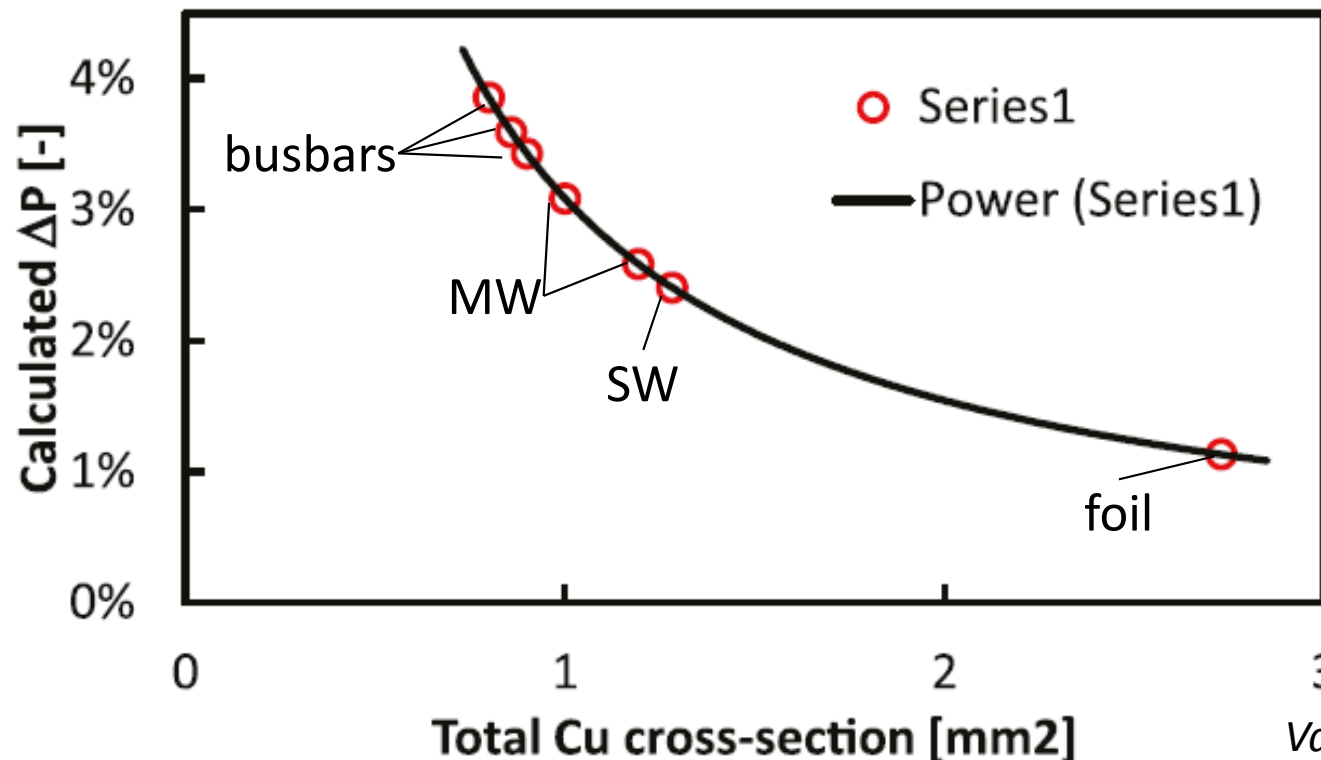
Challenges for glass / polymer back sheet modules

- Optimize CtM:
 - First trials with single cell laminates (next slides)
- Reliability: change and optimize BoM to cope with increased sensitivity towards moisture
 - Work in progress

From MWT HJ cell to module.....

CtM change of the fill factor for various interconnection schemes

- Only resistive losses in interconnection material: tabs, wires, foil
- the calculated power loss is inversely proportional to resistance and thus to the total cross-section of the interconnection material

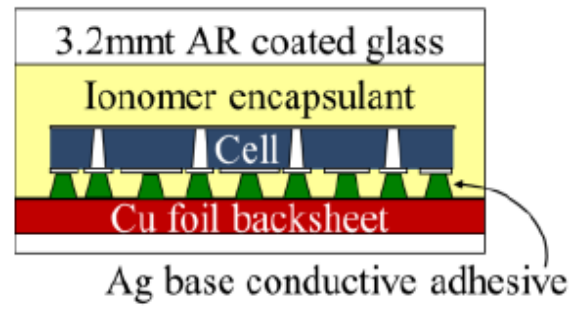
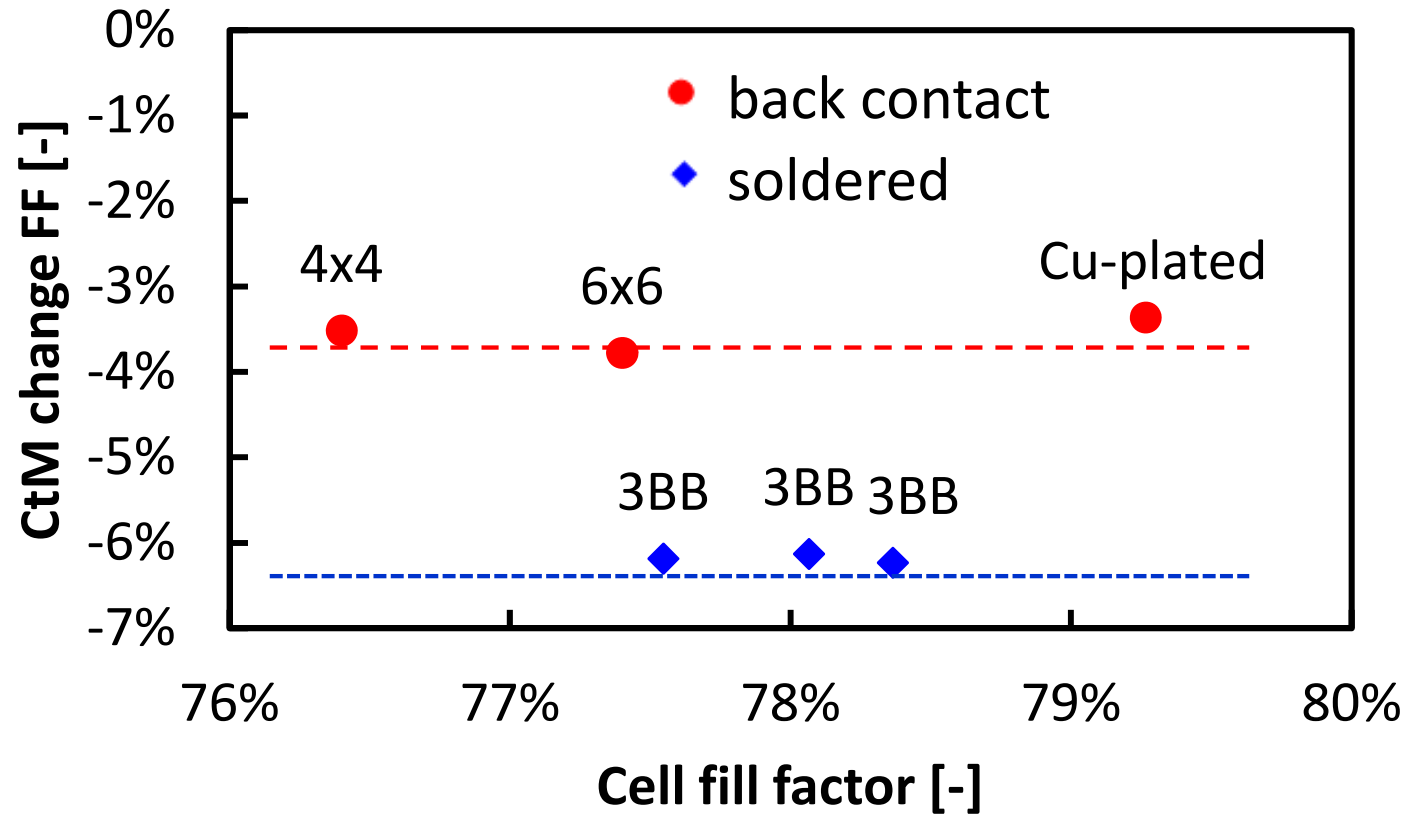


> W_p / m^2

From MWT HJ cell to module.....

CtM change for soldered and back contact single cell laminates

- Electrical layout not optimized: explains larger CtM change
- Relative improvement CtM change BC vs. Soldered



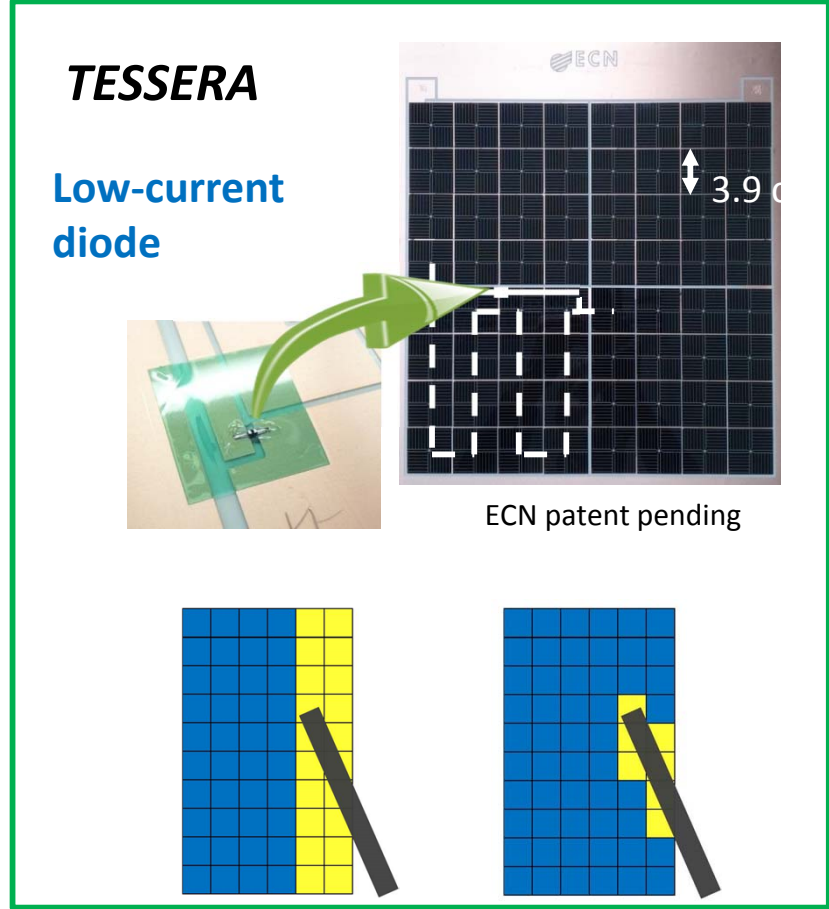
View towards applications

- Broaden applicability: Focus on systems and applications in BIPV
 - aesthetics, uniform appearance
 - size flexibility, shade tolerance
 - freedom of design



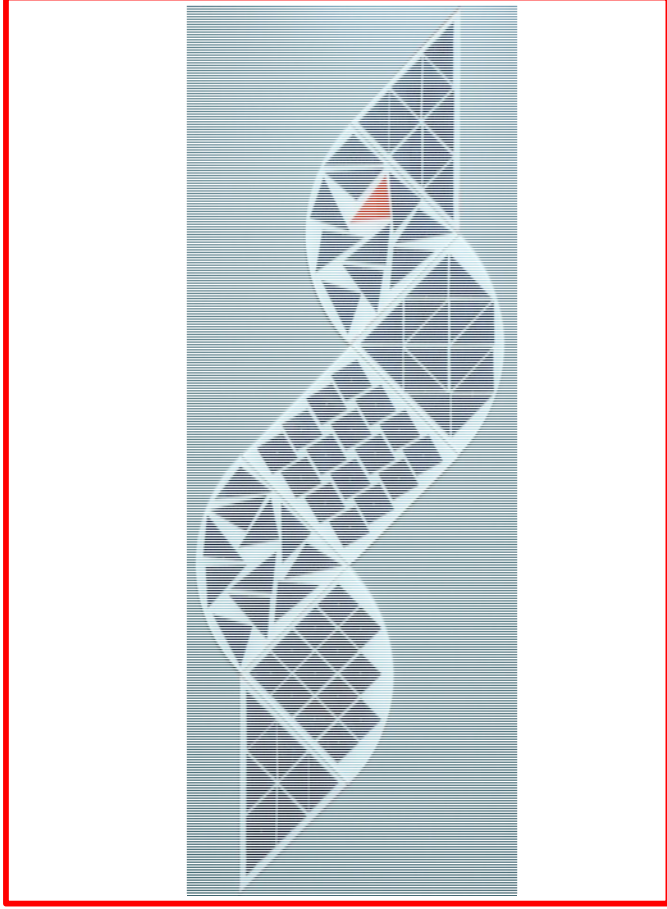
TESSERA

Low-current diode



ECN patent pending

Eurotron, Heliox, Stafier



Summary & Outlook

- All different HE solar cell concepts can be translated to a specific module concept and fulfill all the demands: highest yield, lifetime, low costs,.. there is not one module concept that fits all cell concepts



- Market adoption of new cell and module concepts is not straightforward
 - Incremental improvements preferred
 - Bankability: lack of long term field experience data
- How to accelerate market uptake?
 - Show **competitiveness** by significant performance improvements, cost reduction approaches and field data collection!!
 - Broaden applicability BIPV: Aesthetics, transparency, colours, flexibility of shape & size, etc, I2PV: Bifaciality

Acknowledgements

- MWT – HJ cells/modules

Gianluca Coletti (Coletti@ecn.nl)

Bas van Aken



- Cold spray and powder coating

Maurice Goris (goris@ecn.nl)

Benjamin Kikkert



- Thin cell modules

Paul Sommeling

Lars Okel

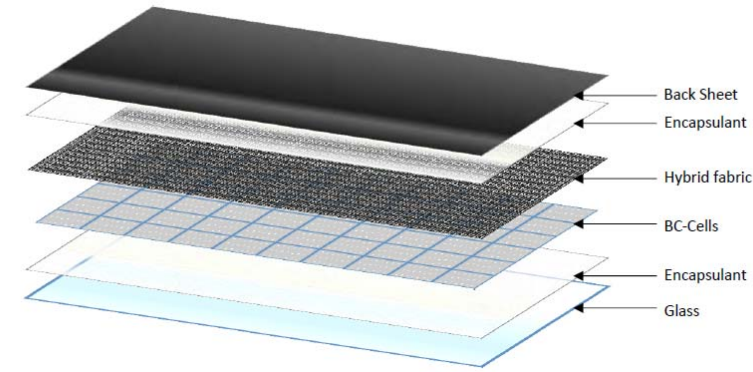
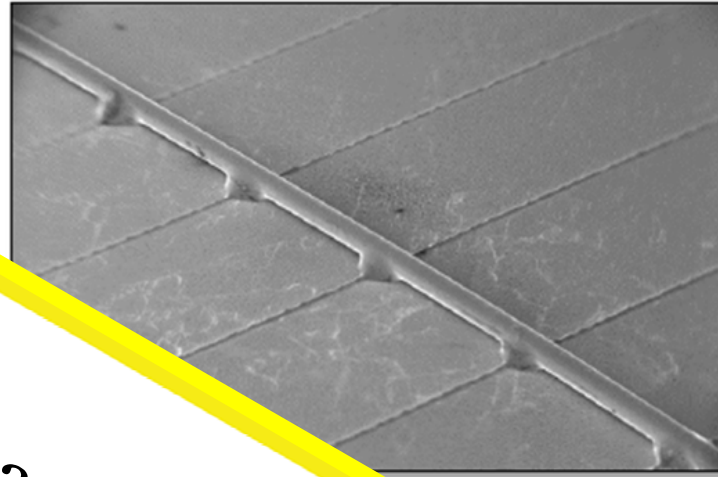
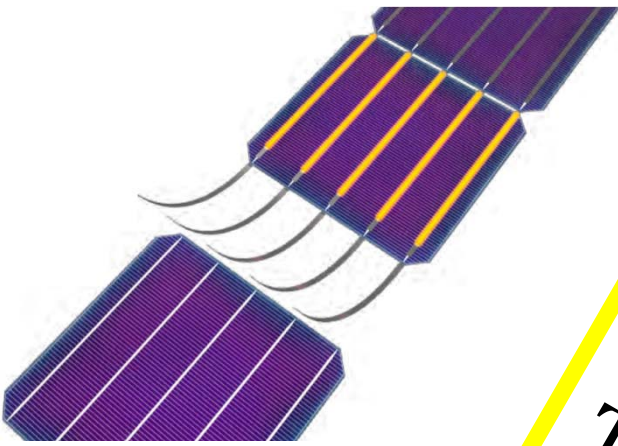


TKI Urban Energy



And all other colleagues that contributed for many years on this development

EC-FP7



Thank you for your attention

